

DNP  
FID1

DNP  
FID2

DNP  
FID3

PCB Number: TIDA-00718  
PCB Rev: A

PCB LOGO  
Texas Instruments

PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer

PCB LOGO

Label Table	
Variant	Label Text
001	TIDA-00718

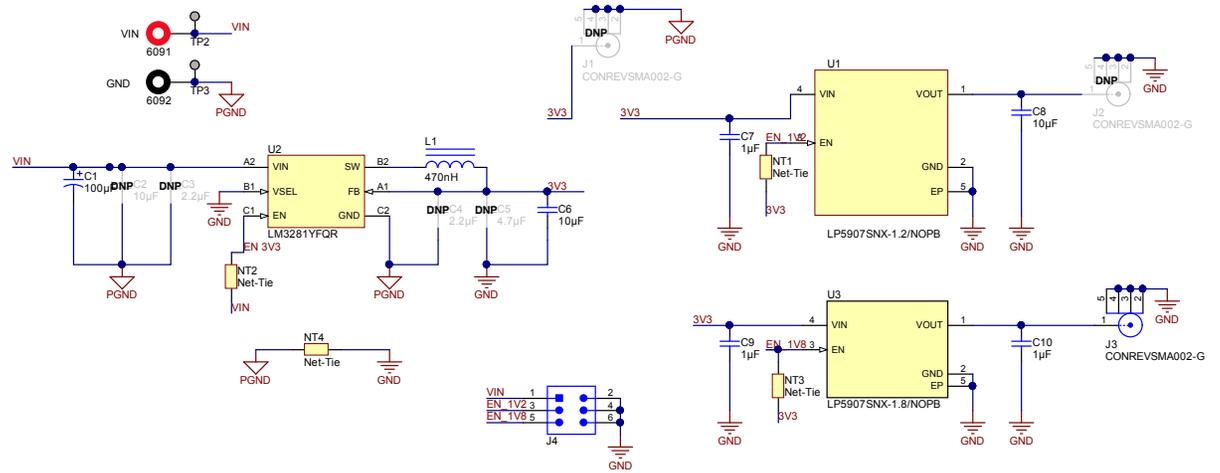
LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



Orderable: N/A	Designed for: Public Release	Mod. Date: 11/24/2015
TID #: 00718	Project Title: Power reference desing for CMOS imagers	
Number: TIDA-00718   Rev: A	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: TIDA-00718_SchDoc	Size: B
Engineer:	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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